

ABSTRACT OF THE DISCLOSURE

A method for collecting semiconductor devices and a method for selling and using semiconductor devices in consideration of collection are provided. When a user of an electrical appliance containing a semiconductor chip discards the electrical appliance, the user disassembles the electrical appliance and removes the semiconductor chip from the printed board on which it is mounted (S1). The user can thus obtain a service number provided on the back (S2) and in step S3 reports the service number to the manufacturer of the electrical appliance, or the manufacturer of the semiconductor chip, or a service organization acting for the purpose of collection. When receiving the report, the manufacturer or the service organization gives a reward to the user (S4) and separately collects the semiconductor chip (S5).

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